



### Power Field Effect Transistor

#### **GENERAL DESCRIPTION**

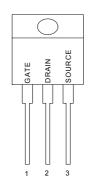
This high voltage MOSFET uses an advanced termination scheme to provide enhanced voltage-blocking capability without degrading performance over time. In addition, this advanced MOSFET is designed to withstand high energy in avalanche and commutation modes. The new energy efficient design also offers a drain-to-source diode with a fast recovery time. Designed for high voltage, high speed switching applications in power supplies, converters and PWM motor controls, these devices are particularly well suited for bridge circuits where diode speed and commutating safe operating areas are critical and offer additional and safety margin against unexpected voltage transients.

#### **FEATURES**

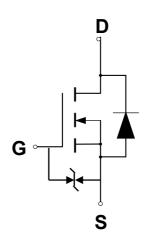
- Robust High Voltage Termination
- Avalanche Energy Specified
- ◆ Source-to-Drain Diode Recovery Time Comparable to a Discrete Fast Recovery Diode
- Diode is Characterized for Use in Bridge Circuits
- ♦ I<sub>DSS</sub> and V<sub>DS</sub>(on) Specified at Elevated Temperature

### **PIN CONFIGURATION**





#### SYMBOL



N-Channel MOSFET

#### **ABSOLUTE MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Drain to Current — Continuous	I <sub>D</sub>	9.7	Α
- Pulsed	I <sub>DM</sub>	29.1	
Gate-to-Source Voltage — Continue	$V_{GS}$	±30	V
Total Power Dissipation (TO220)	P <sub>D</sub>	142	W
(TO220F)		44	
Derate above 25℃ (TO220)		1.12	W/°C
(TO220F)		0.36	
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to 150	$^{\circ}\mathbb{C}$
Single Pulse Drain-to-Source Avalanche Energy $ T_J$ = $25^{\circ}$ C	E <sub>AS</sub>	361	mJ
$(V_{DD} = 100V, V_{GS} = 10V, I_{L} = 8.5A, L = 10mH, R_{G} = 25\Omega)$			
Thermal Resistance — Junction to Case (TO220)	θ <sub>JC</sub>	0.89	°CW
(TO220F)		3.9	
<ul> <li>Junction to Ambient</li> </ul>	$\theta_{JA}$	62.5	
Maximum Lead Temperature for Soldering Purposes, 1/8" from case for 10 seconds	T∟	260	$^{\circ}\!\mathbb{C}$
ESD SENSITIVITY — HBM, C=100pF, R=1.5kΩ	Vesd	2000	V





## POWER FIELD EFFECT TRANSISTOR

### **ORDERING INFORMATION**

Part Number	Package
GPT10N50ADGN220FP*	TO-220F
GPT10N50AGN220*	TO-220

<sup>\*</sup>Note: G: Suffix for PB Free Product

### **ELECTRICAL CHARACTERISTICS**

Unless otherwise specified,  $T_J = 25^{\circ}C$ .

			GPT10N50A			
Cha	racteristic	Symbol	Min	Тур	Max	Units
Drain-Source Breakdown Voltage		V <sub>(BR)DSS</sub>	500			V
$(V_{GS} = 0 \text{ V}, I_D = 250 \ \mu \text{ A})$						
Drain-Source Leakage Current		$I_{DSS}$			1	μΑ
$(V_{DS} = 500 \text{ V}, V_{GS} = 0 \text{ V})$						
Gate-Source Leakage Current-Forward		$I_{GSSF}$			100	nA
$(V_{gsf} = 30 \text{ V}, V_{DS} = 0 \text{ V})$						
Gate-Source Leakage Current-Reverse		$I_{GSSR}$			100	nA
$(V_{gsr} = -30 \text{ V}, V_{DS} = 0 \text{ V})$						
Gate Threshold Voltage		$V_{GS(th)}$	2.5		4.5	V
$(V_{DS} = V_{GS}, I_{D} = 250 \ \mu A)$						
Static Drain-Source On-Resistance (V <sub>GS</sub> = 10 V, I <sub>D</sub> = 5A) *		R <sub>DS(on)</sub>			0.7	Ω
Forward Transconductance (V <sub>DS</sub>	= 15 V, I <sub>D</sub> = 5A) *	<b>9</b> FS		8		S
Input Capacitance	$(V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V}.$	C <sub>iss</sub>		1149		pF
Output Capacitance	f = 1.0 MHz)	Coss		124.3		pF
Reverse Transfer Capacitance		C <sub>rss</sub>		9.19		pF
Turn-On Delay Time	$(V_{DD} = 250 \text{ V}, I_{D} = 10 \text{ A},$ $R_{G} = 25\Omega) *$	$t_{d(on)}$		20.8		ns
Rise Time		t <sub>r</sub>		28		ns
Turn-Off Delay Time		$t_{d(off)}$		42.4		ns
Fall Time		t <sub>f</sub>		25.6		ns
Total Gate Charge	$(V_{DS} = 400 \text{ V}, I_D = 10 \text{ A}, V_{GS} = 10 \text{ V})^*$	$Q_g$		26.7		nC
Gate-Source Charge		Q <sub>gs</sub>		6.08		nC
Gate-Drain Charge		$Q_gd$		10.9		nC
SOURCE-DRAIN DIODE CHARA	ACTERISTICS		•			•
Forward On-Voltage(1)	$(I_S = 10 \text{ A}, V_{GS} = 0 \text{ V}, \\ d_{IS}/d_t = 100\text{A}/\mu\text{s})$	V <sub>SD</sub>			1.5	V
Forward Turn-On Time		t <sub>on</sub>		**		ns
Reverse Recovery Time		t <sub>rr</sub>		378.7		ns

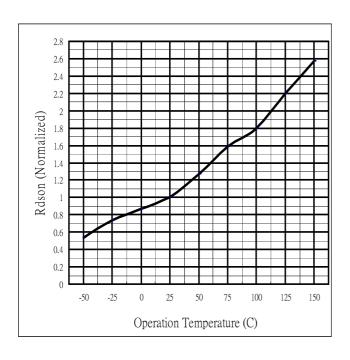
<sup>\*</sup> Pulse Test: Pulse Width  $\leq$ 300 $\mu$ s, Duty Cycle  $\leq$ 2%

<sup>\*\*</sup> Negligible, Dominated by circuit inductance



### Power Field Effect Transistor

#### TYPICAL ELECTRICAL CHARACTERISTICS



1.2 (Poziliem 1) (

Fig 1. On-Resistance Vs. Temperature

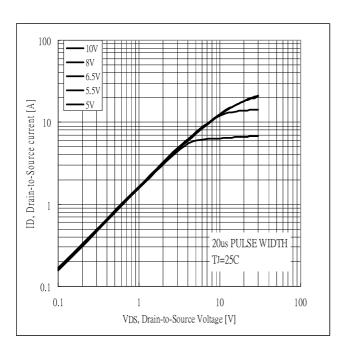


Fig 2. Typical Output Characteristics

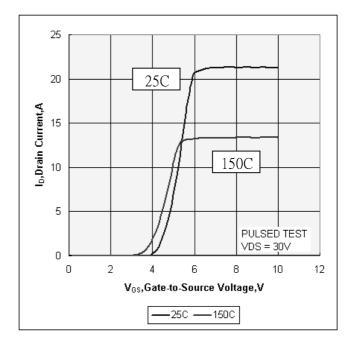


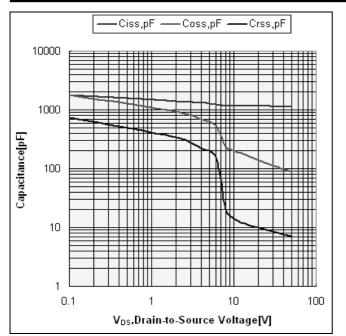
Fig 3. Typical Output Characteristics

Fig 4. Typical Transfer Characteristics





Power Field Effect Transistor



10 V<sub>DS</sub> = 480V V<sub>DS</sub> = 300V V<sub>GS</sub>, Gate-to-Source Voltage[V] V<sub>DS</sub> = 120V 4 2 5 10 15 20 25 30 35 40 Q<sub>G</sub>,Total Gate Charge[nC]

Fig 5. Typical Capacitance Vs. Drain-to-Source Voltage

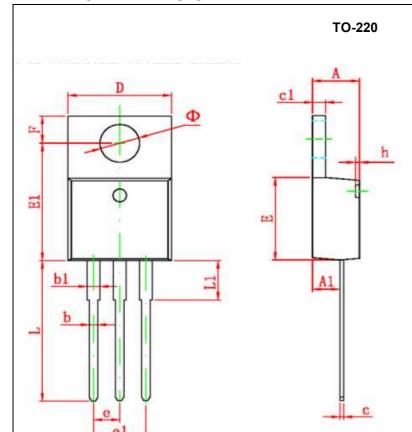
Fig 6. Typical Gate Charge Vs. Gate-to-Source Voltage





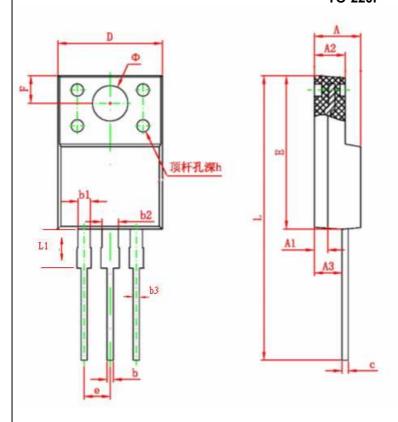
POWER FIELD EFFECT TRANSISTOR

### **PACKAGE DIMENSION**



Completed	Dimensions In Millimeters		
Symbol	Min.	Max	
Α	4.40	4.80	
A1	2.10	2.84	
Ъ	0.71	0.91	
b1	1.17	1.37	
С	0.30	0.60	
c1	1.17	1.47	
D	9.40	10.60	
Е	8.40	9.60	
е	2.54 TYP.		
e1	4.90	5.60	
F	3.00 REF.		
Φ	3.50 REF.		
h	0.00	0.30	
L	12.50	14.00	
L1	3.50	4.00	

### TO-220F



C1 -1	Dimensions In Millimeters		
Symbol	Min.	Max	
A	3.80	4.70	
A1	1.3 REF.		
A2	2.20	3.20	
A3	2.10	3,20	
ь	0.30	0.95	
b1	1.00	1.75	
Ъ2	1.00	1.75	
ъ3	0.50	0.80	
U	0.30	0.90	
D	9.90	10.40	
E	14.60	16.20	
е	2.54 TYP.		
F	3.00 REF.		
Φ	3.50 REF.		
h	0.00	0.30	
L	28.00	30.00	
Ll	3.20	3.55	





POWER FIELD EFFECT TRANSISTOR

#### **IMPORTANT NOTICE**

Great Power Microelectronic Corporation (GP) reserves the right to make changes to its products or to discontinue any integrated circuit product or service without notice, and advises its customers to obtain the latest version of relevant information to verify, before placing orders, that the information being relied on is current.

A few applications using integrated circuit products may involve potential risks of death, personal injury, or severe property or environmental damage. GP integrated circuit products are not designed, intended, authorized, or warranted to be suitable for use in life-support applications, devices or systems or other critical applications. Use of GP products in such applications is understood to be fully at the risk of the customer. In order to minimize risks associated with the customer's applications, the customer should provide adequate design and operating safeguards.



虹冠電子工業股份有限公司 Champion Microelectronic Corporation Web:http://www.champion-micro.com/



深圳市冠顺微电子股份有限公司 Shenzhen Great Power Co., Ltd Web:http://www.grtpower.com

臺灣深均

新北市汐止區新台五路一段 96 號 21F

21F., No. 96, Sec. 1, Sintai 5th Rd., Sijhih City, Taipei County 22102,

Taiwan, R.O.C.

TEL: +886-2-2696 3558 FAX: +886-2-2696 3559 深圳市福田区深南大道 7002 号财富广场 A座 4V,

4V, Tower A, Fortune Plaza, No. 7002, Shennan Road, Futian District, Shenzhen City, China

PC : 518040

TEL: +86-755-83709176 FAX: +86-755-83709276